



SEMITRANS® 2

Fast IGBT4 Modules

SKM50GAL12T4

Features

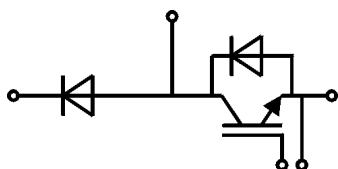
- $V_{CE(sat)}$ with positive temperature coefficient
- High short circuit capability, self limiting to $6 \times I_{Cnom}$
- Fast & soft inverse CAL diodes
- Large clearance (10 mm) and creepage distances (20 mm)
- Isolated copper baseplate using DBC Technology (Direct Copper Bonding)
- UL recognized, file no. E63532

Typical Applications*

- DC/DC – converter
- Brake chopper
- Switched reluctance motor
- DC – motor

Remarks

- Case temperature limited to $T_c = 125^\circ\text{C}$ max, recomm.
 $T_{op} = -40 \dots +150^\circ\text{C}$, product rel. results valid for $T_j = 150^\circ$



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Absolute Maximum Ratings				
Symbol	Conditions		Values	Unit
IGBT				
V _{CES}	T _j = 25 °C		1200	V
I _C	T _j = 175 °C	T _c = 25 °C	81	A
		T _c = 80 °C	62	A
I _{Cnom}			50	A
I _{CRM}	I _{CRM} = 3xI _{Cnom}		150	A
V _{GES}			-20 ... 20	V
t _{psc}	V _{CC} = 800 V V _{GE} ≤ 15 V V _{CES} ≤ 1200 V	T _j = 150 °C	10	µs
T _j			-40 ... 175	°C
Inverse diode				
I _F	T _j = 175 °C	T _c = 25 °C	65	A
		T _c = 80 °C	49	A
I _{Fnom}			50	A
I _{FRM}	I _{FRM} = 3xI _{Fnom}		150	A
I _{FSM}	t _p = 10 ms, sin 180°, T _j = 25 °C		270	A
T _j			-40 ... 175	°C
Freewheeling diode				
I _F	T _j = 175 °C	T _c = 25 °C	65	A
		T _c = 80 °C	49	A
I _{Fnom}			50	A
I _{FRM}	I _{FRM} = 3xI _{Fnom}		150	A
I _{FSM}	t _p = 10 ms, sin 180°, T _j = 25 °C		270	A
T _j			-40 ... 175	°C
Module				
I _{t(RMS)}	T _{terminal} = T _{terminal} < 80 °C		200	A
T _{stg}			-40 ... 125	°C
V _{isol}	AC sinus 50Hz, t = 1 min		4000	V

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
IGBT						
V _{CE(sat)}	I _C = 50 A V _{GE} = 15 V chipselevel	T _J = 25 °C		1.85	2.1	V
		T _J = 150 °C		2.2	2.4	V
V _{CE0}		T _J = 25 °C		0.8	0.9	V
		T _J = 150 °C		0.7	0.8	V
r _{CE}	V _{GE} = 15 V	T _J = 25 °C		21.0	24.0	mΩ
		T _J = 150 °C		30.0	32.0	mΩ
V _{GE(th)}	V _{GE} =V _{CE} , I _C = 1.7 mA		5	5.8	6.5	V
I _{CES}	V _{GE} = 0 V	T _J = 25 °C		0.1	0.3	mA
	V _{CE} = 1200 V	T _J = 150 °C				mA
C _{ies}	V _{CE} = 25 V V _{GE} = 0 V	f = 1 MHz		2.77		nF
C _{oes}		f = 1 MHz		0.20		nF
C _{res}		f = 1 MHz		0.16		nF
Q _G	V _{GE} = - 8 V...+ 15 V			280		nC
R _{Gint}	T _j = 25 °C			4.0		Ω



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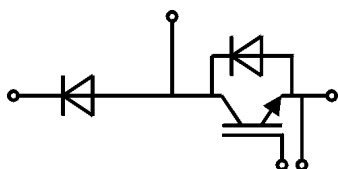
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Remarks

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Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
t _{d(on)}	V _{CC} = 600 V	T _j = 150 °C		98		ns
t _r	I _C = 50 A	T _j = 150 °C		29		ns
E _{on}	V _{GE} = ±15 V	T _j = 150 °C		5.5		mJ
t _{d(off)}	R _{G on} = 8.2 Ω	T _j = 150 °C		325		ns
t _f	R _{G off} = 8.2 Ω	T _j = 150 °C		75		ns
E _{off}	di/dt _{on} = 1700 A/μs di/dt _{off} = 670 A/μs	T _j = 150 °C		4.5		mJ
R _{th(j-c)}	per IGBT				0.53	K/W
Inverse diode						
V _F = V _{EC}	I _F = 50 A	T _j = 25 °C		2.22	2.54	V
	V _{GE} = 0 V chip	T _j = 150 °C		2.18	2.50	V
V _{F0}		T _j = 25 °C		1.3	1.5	V
		T _j = 150 °C		0.9	1.1	V
r _F		T _j = 25 °C		18.4	20.8	mΩ
		T _j = 150 °C		25.6	28.0	mΩ
I _{RRM}	I _F = 50 A	T _j = 150 °C		35		A
Q _{rr}	di/dt _{off} = 1380 A/μs	T _j = 150 °C		8.7		μC
E _{rr}	V _{GE} = ±15 V V _{CC} = 600 V	T _j = 150 °C		3.6		mJ
R _{th(j-c)}	per diode				0.84	K/W
Freewheeling diode						
V _F = V _{EC}	I _F = 50 A	T _j = 25 °C		2.22	2.54	V
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Q _{rr}	di/dt _{off} = 1380 A/μs	T _j = 150 °C		8.7		μC
E _{rr}	V _{GE} = ±15 V V _{CC} = 600 V	T _j = 150 °C		3.6		mJ
R _{th(j-c)}	per Diode				0.84	K/W
Module						
L _{CE}					30	nH
R _{CC'+EE'}	terminal-chip	T _C = 25 °C		0.65		mΩ
		T _C = 125 °C		1		mΩ
R _{th(c-s)}	per module			0.04	0.05	K/W
M _s	to heat sink M6		3		5	Nm
M _t		to terminals M5	2.5		5	Nm
						Nm
w					160	g



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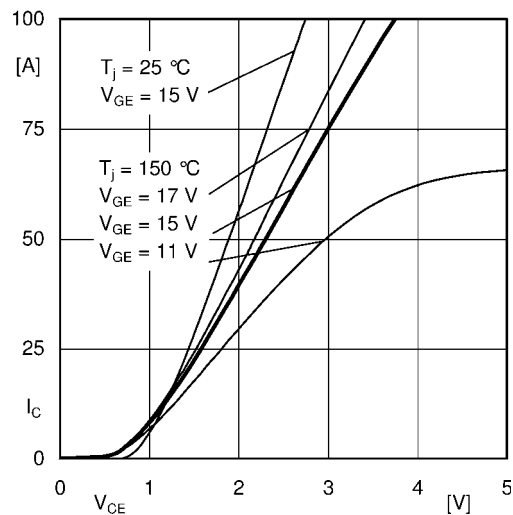


Fig. 1: Typ. output characteristic, inclusive $R_{CC'} + EE'$

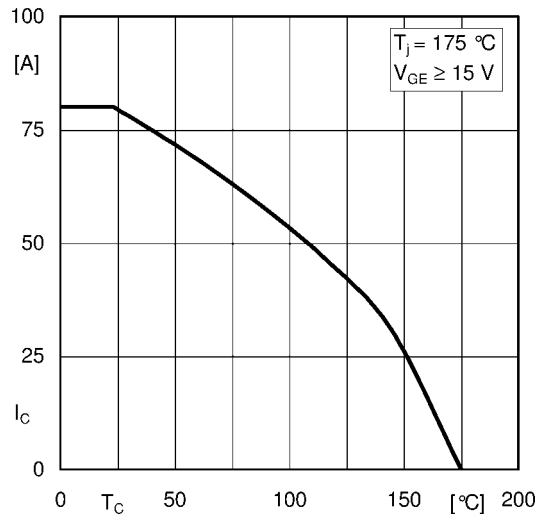


Fig. 2: Rated current vs. temperature $I_C = f(T_C)$

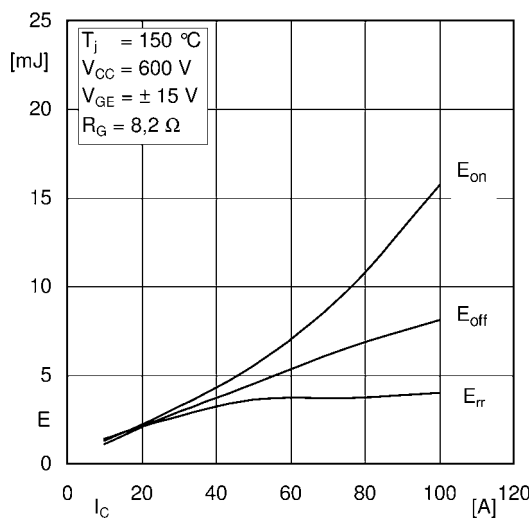


Fig. 3: Typ. turn-on /-off energy = $f(I_C)$

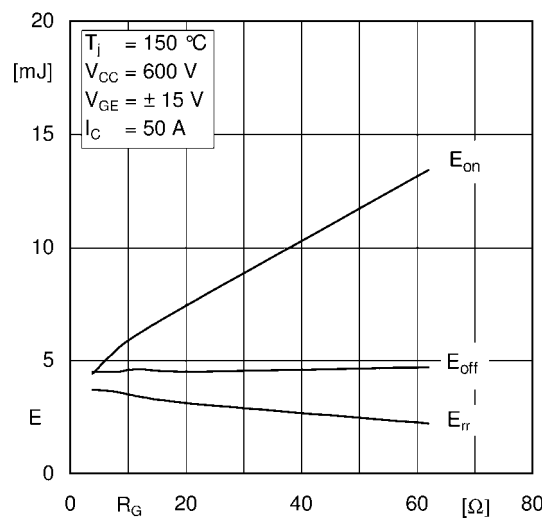


Fig. 4: Typ. turn-on /-off energy = $f(R_G)$

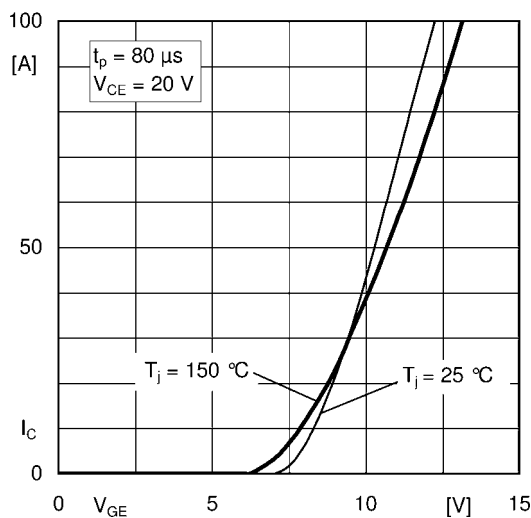


Fig. 5: Typ. transfer characteristic

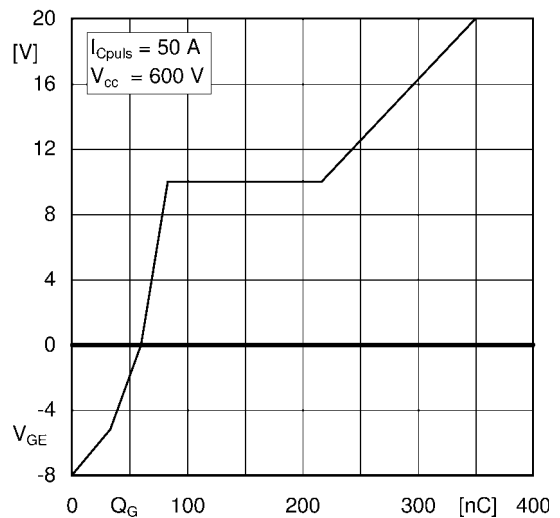


Fig. 6: Typ. gate charge characteristic

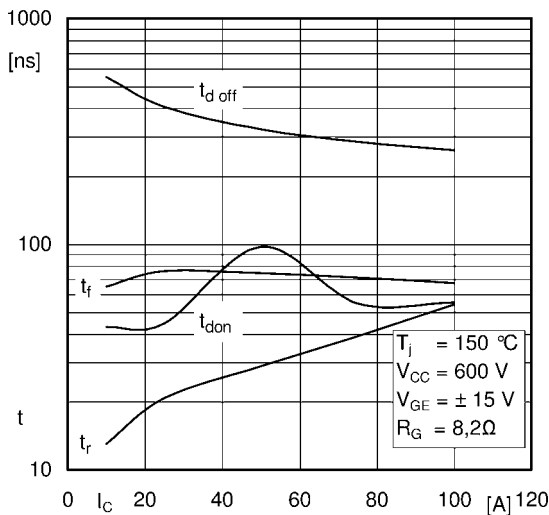


Fig. 7: Typ. switching times vs. I_C

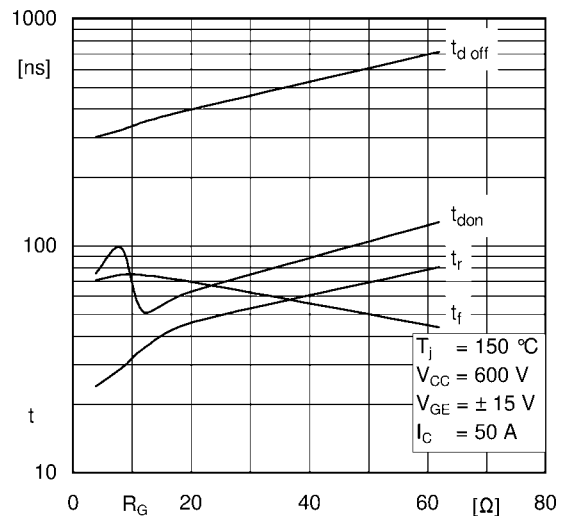


Fig. 8: Typ. switching times vs. gate resistor R_G

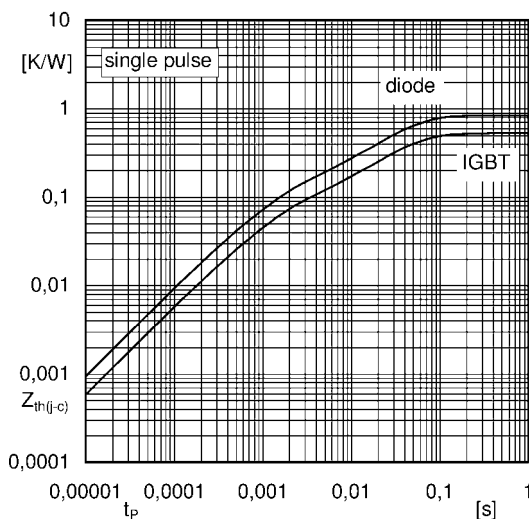


Fig. 9: Transient thermal impedance

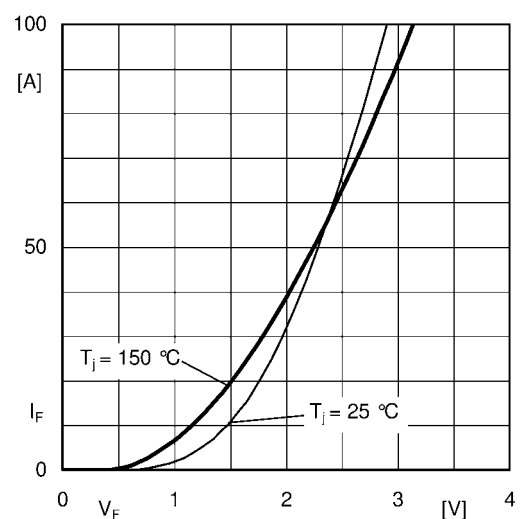


Fig. 10: Typ. CAL diode forward charact., incl. $R_{CC'+EE'}$

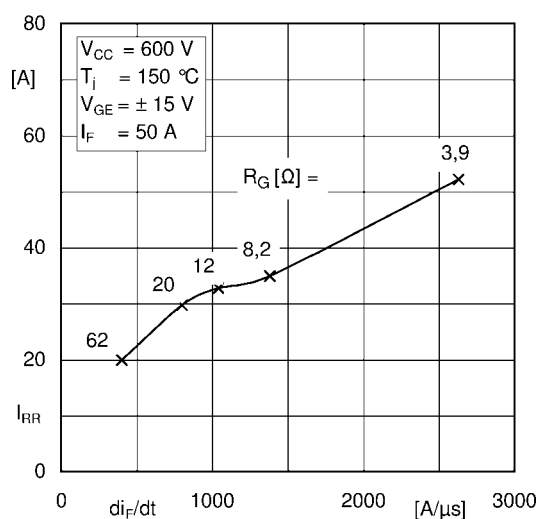


Fig. 11: CAL diode peak reverse recovery current

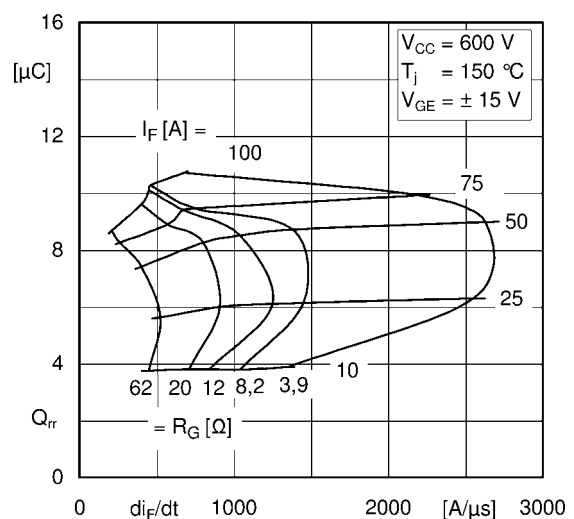
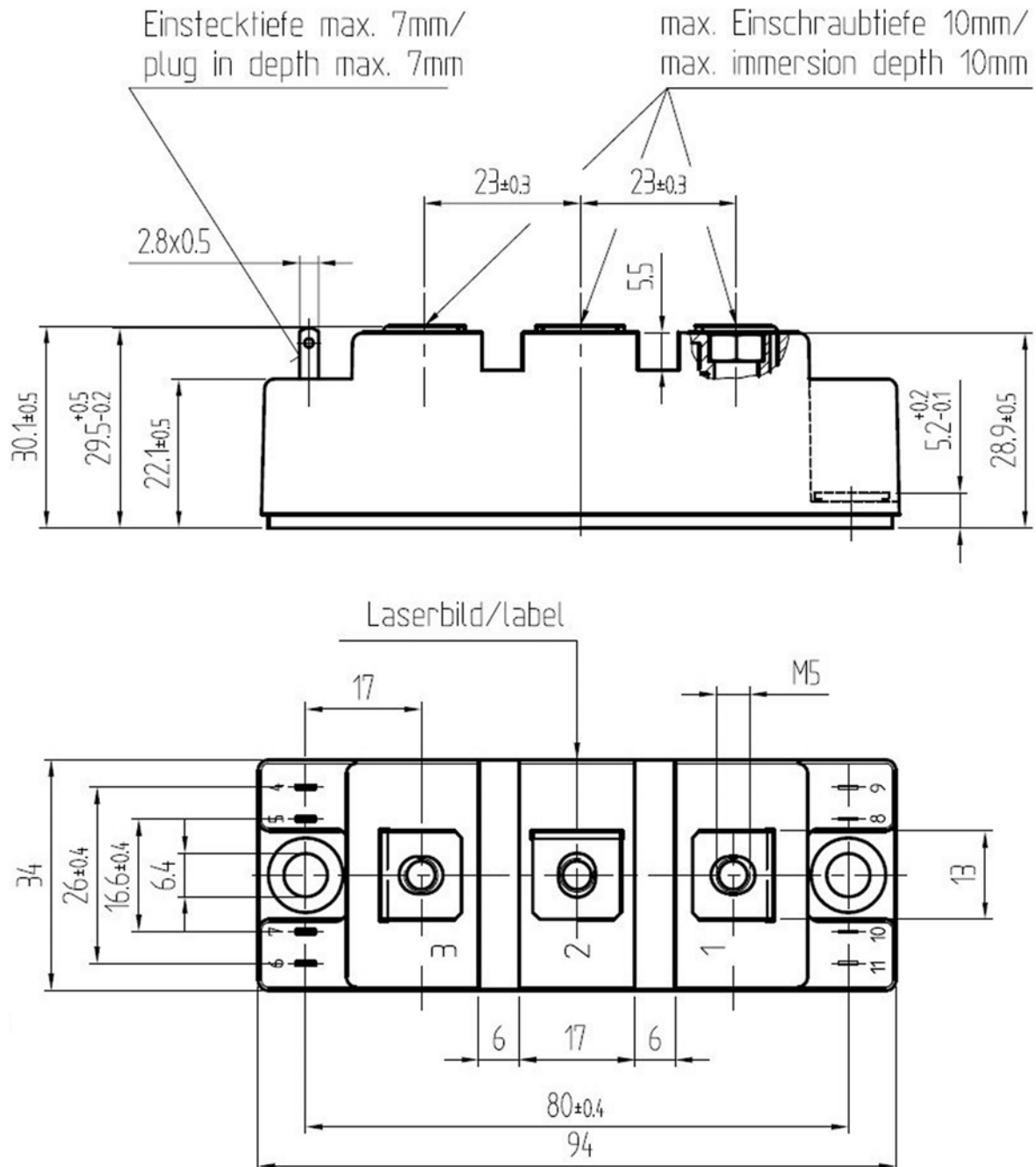
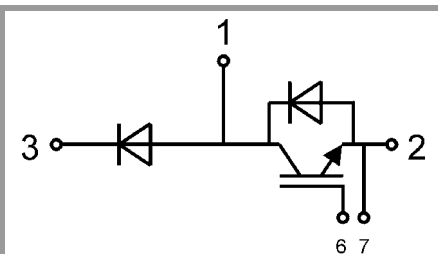


Fig. 12: Typ. CAL diode peak reverse recovery charge



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This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our personal.